



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

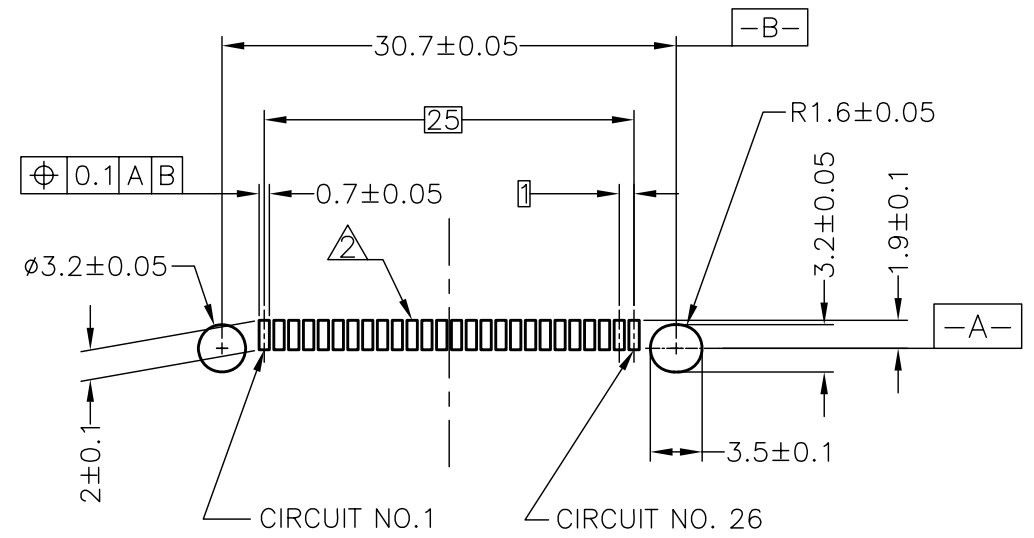
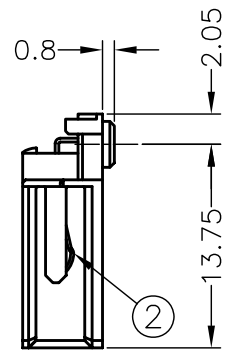
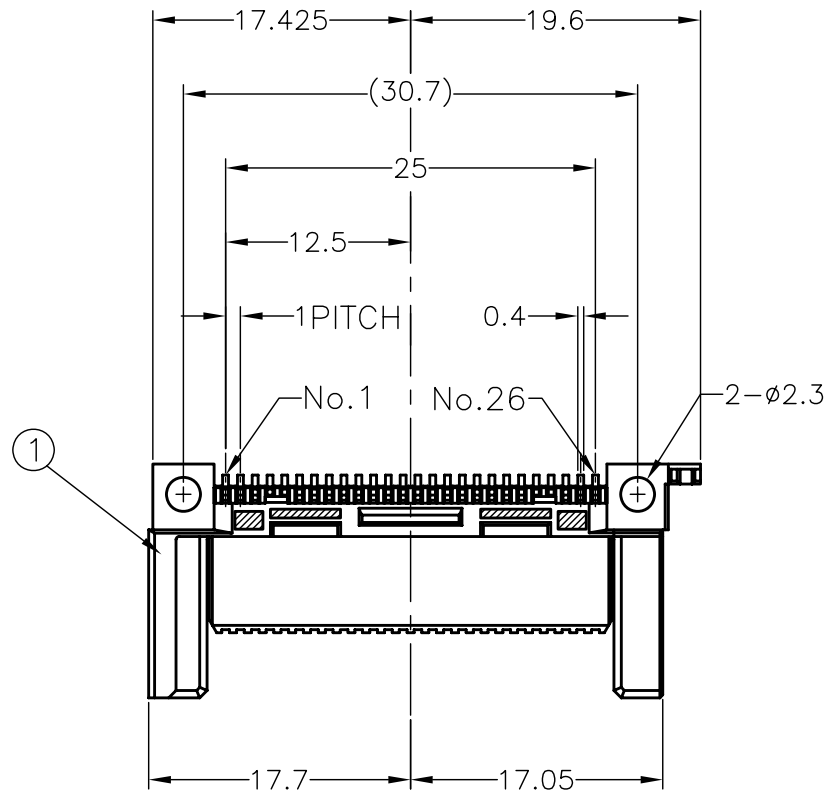
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



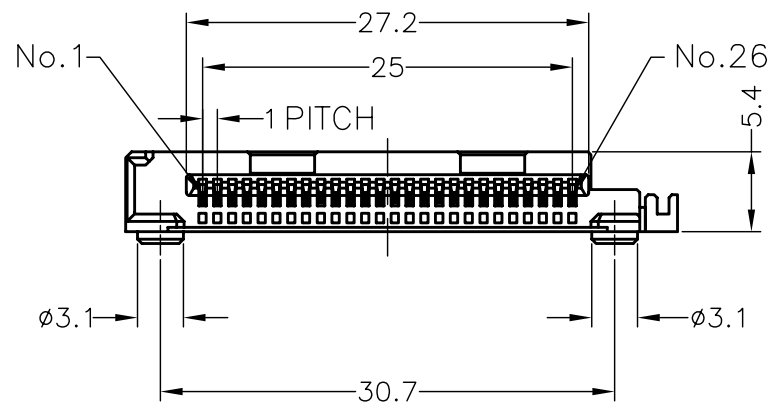
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LOC	DIST	REVISIONS					
DW		P	LTR	DESCRIPTION	DATE	DWN	APVD
		C		REVISED (ECR-08-023963)	18SEP08	W.C	H.K



REFERENCE P.C.BOARD LAYOUT
 GENERAL TOLERANCE ±0.05
 (SCALE: 2:1)
 (HEADER CONNECTOR MOUNTING LAYOUT DETAIL)



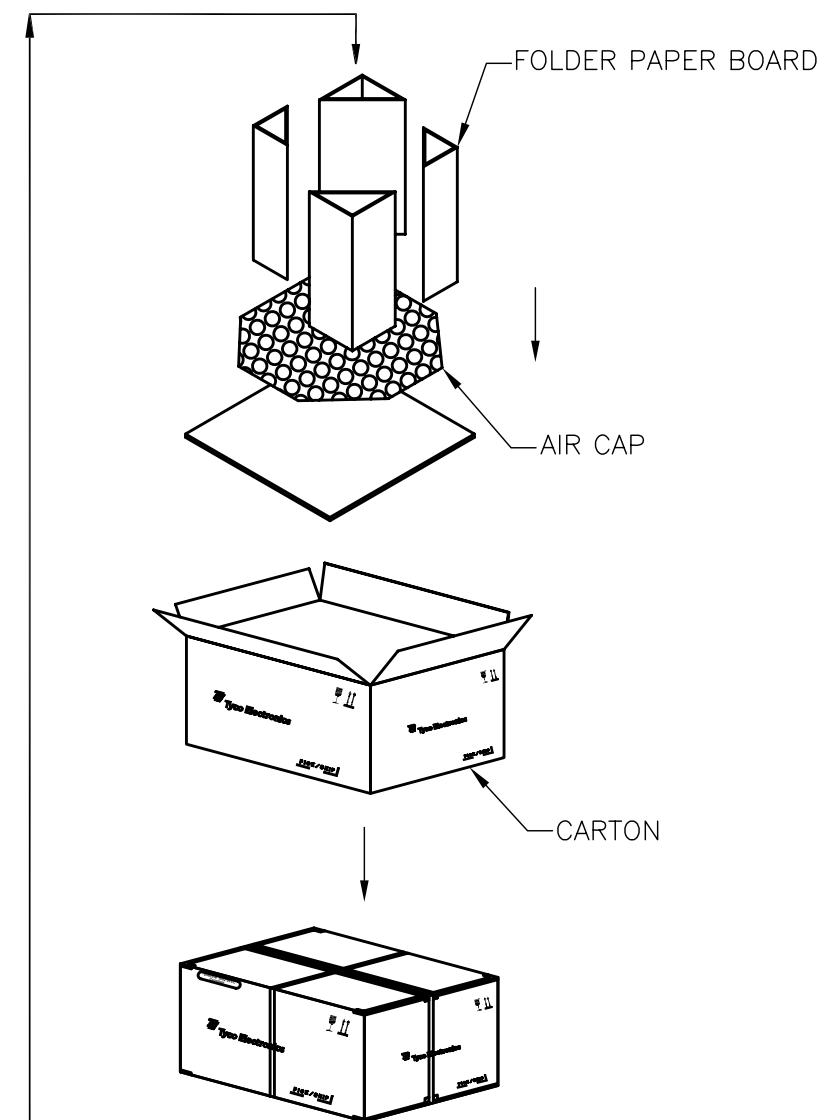
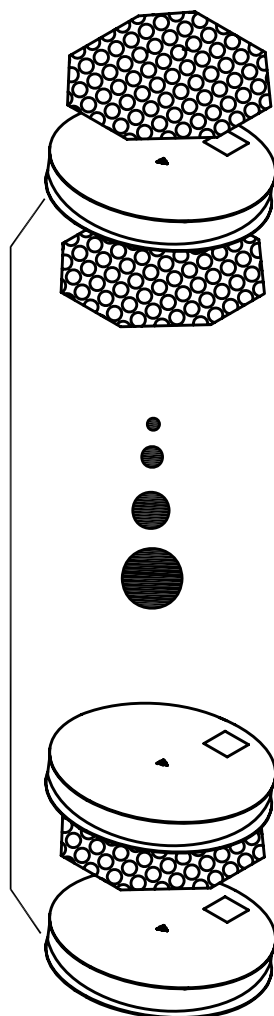
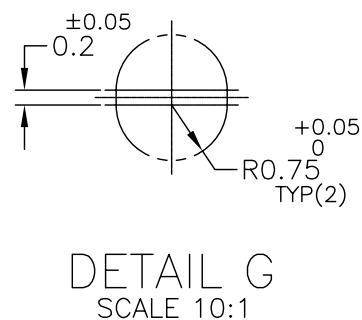
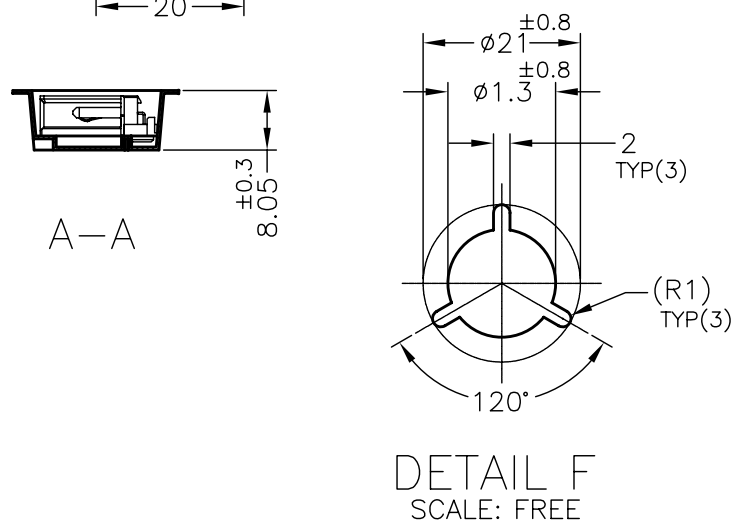
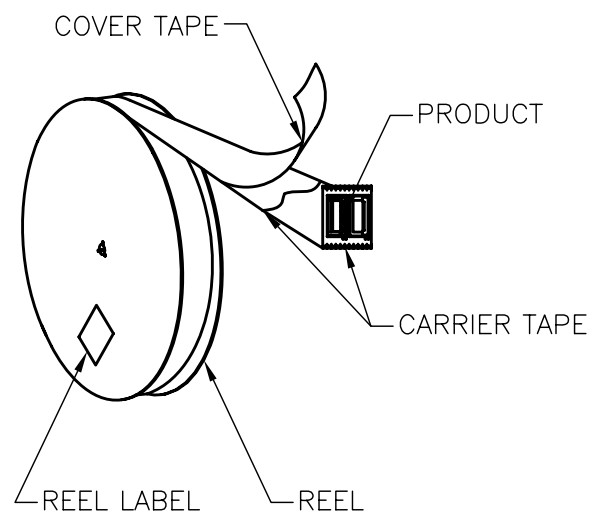
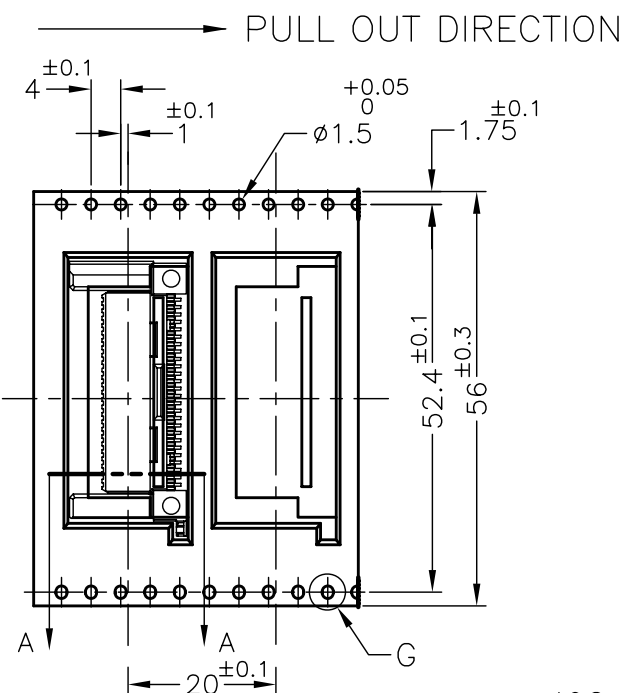
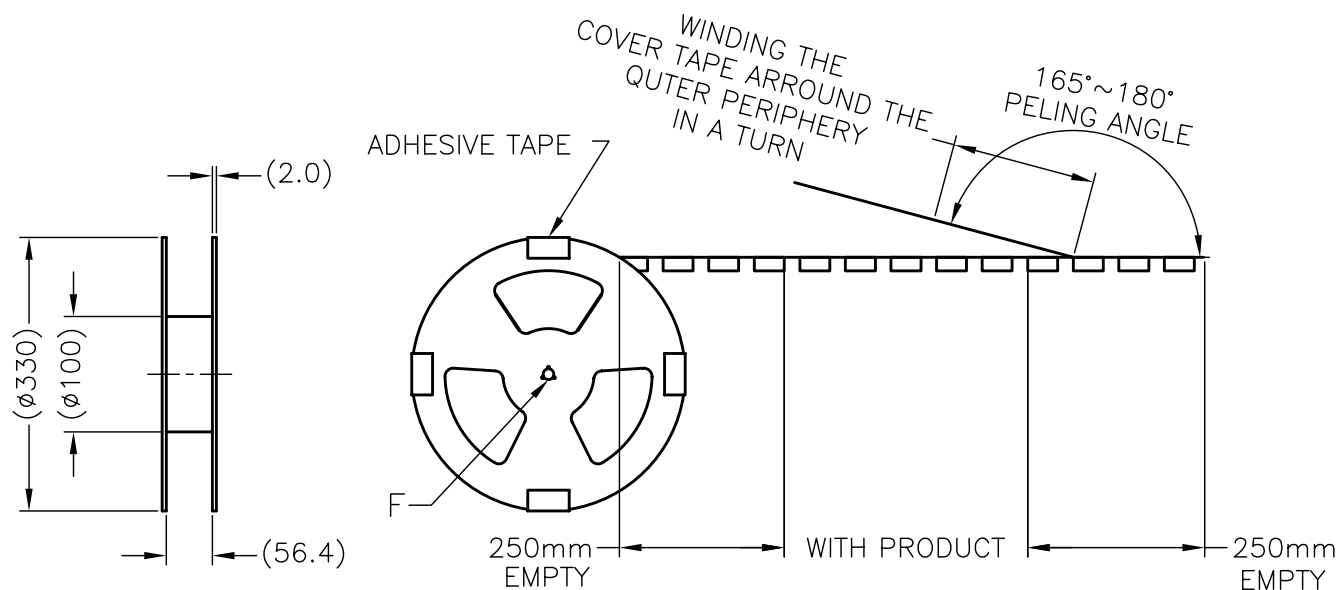
COPPER ALLOY Au 0.000381mm MIN., TIN 0.002mm MIN. Ni 0.00127mm MIN. UNDERPLATING ALL OVER	HIGH TEMP THERMOPLASTIC UL94 V-0 COLOR:BLACK	26	1759011-2
COPPER ALLOY Au 0.0002mm MIN., TIN 0.002mm MIN. Ni 0.00127mm MIN. UNDERPLATING ALL OVER	HIGH TEMP THERMOPLASTIC UL94 V-0 COLOR:BLACK	26	1759011-1
② CONTACT	① HEADER HSG	POS.	PART NUMBER
MATERIAL & FINISH			

1. BE USE ALTOGETHER THE HEADER AND TYCO ELECTRONICS'S FRAME
 SOLDER PAD

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN M.CHAO 16FEB05	Tyco Electronics Corporation Taipei, Taiwan	
DIMENSIONS: mm		CHK T.FUTATSUGI 16FEB05	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 0.5 1 PLC ± 0.5 2 PLC ± 0.5 3 PLC ± 0.5 4 PLC ± 0.5 ANGLES ± 1'		APVD H.KODAMA 16FEB05	PRODUCT SPEC 108-99000	
MATERIAL		FINISH	APPLICATION SPEC	RESTRICTED TO
		WEIGHT 1.25 g	SIZE A3	CAGE CODE 00779
		CUSTOMER DRAWING	DRAWING NO C-1759011	SCALE 2:1
			SHEET 1 OF 2	REV C

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LOC	DIST	REVISIONS		
DW	/	P	LTR	DESCRIPTION
				DATE
				DWN
				APVD
				—
				—
				—



3. PACKING MATERIAL: CARRIER TAPE: HIPS; COLOR: CLEAR.
 COVER TAPE: PET; COLOR: CLEAR.
 4. CARTON DIMENSIONS: 355X355X310

350	4	1400
PCS/REEL	REEL/CARTON	TOTAL Q'TY

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN	CHK	APVD	PRODUCT SPEC	APPLICATION SPEC	WEIGHT	CUSTOMER DRAWING		
Tyco Electronics Corporation Taipei, Taiwan						NAME HEADER ASSEMBLY TOP MOUNT, CARD PUSH TYPE ExpressCard CONNECTOR		
DIMENSIONS: mm		TOLERANCES UNLESS OTHERWISE SPECIFIED:		SIZE		CAGE CODE	DRAWING NO	RESTRICTED TO
0 PLC ± 1 1 PLC ± 1 2 PLC ± 1 3 PLC ± 1 4 PLC ± 1 ANGLES ± 3°		MATERIAL FINISH		A3	00779	C-1759011		
SCALE 1:1						SHEET 2 OF 2		REV C